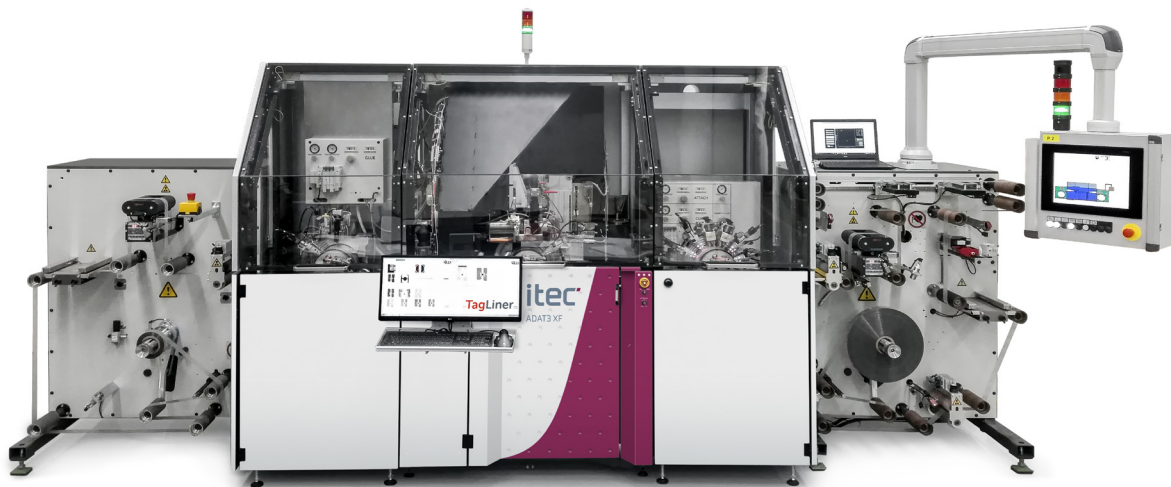


# ADAT3 XF Tagliner Featuring Tagsurance<sup>®</sup> 3

ITEC is a semiconductor equipment company that produces a range of products, including die attach equipment, test and vision equipment, and software solutions for process optimization. ITEC excels at high volume, high speed, and high accuracy semiconductor manufacturing.

ITEC's customers benefit from the company's sustainable and upgradable manufacturing solutions

that can deliver the output with a very competitive total cost of ownership. With an installed base of more than 2,500 of the industry's most advanced tools, ITEC enables its customers to assemble and test 250 million semiconductors every single day. On a mission to redefine semiconductor manufacturing, ITEC constantly pushes the boundaries of semiconductor productivity.



## **ADAT3 XF Tagliner:** The highest productivity and quality standard at the lowest cost of ownership

Curing in milliseconds rather than seconds commonly used in the industry, the ADAT3 XF Tagliner is three times faster and 30% more accurate than anything on the market.

Common systems only work with transparent web material; the ADAT3 XF Tagliner handles a diverse range, including paper, enabling you to move away from PET for sustainability reasons.

Eliminating manual handling through automated wafer change and qualified for die bonding of all known ICs down to 200 µm die size, the ADAT3 XF Tagliner performs a complete inspection without sacrificing speed and productivity.

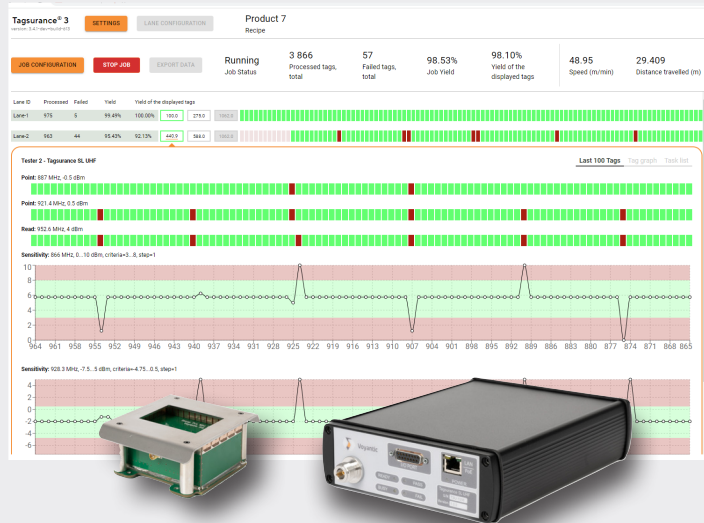
## KEY FEATURES

- 48.000 UPH throughput up to 50.8 mm web pitch
- High-precision die-attach (< 9 micron @ 1 sigma)
- Works with both transparent and non-transparent web material
- High-precision glue dispense system
- High-speed thermal compression curing system.
- Easy maintenance, one or two units only
- 100% high-resolution optical inspections on glue dispense, die attach and cure processes – without compromising machine speed
- Process fully qualified for major chip types at the industry's most stringent reliability requirements: temperature, humidity, and mechanical (die shear)
- 8 to 12 inches wafer compatible with fully automatic wafer change
- Capable of handling dies as small as 200 µm
- Single-track design for easy operation and change over
- Integrated with BW Paper systems' winding/conversion systems
- Integrated with **Voyantic Tagsurance Quality Control system**

## Quality Control with Tagsurance 3

The Tagsurance system gives full visibility into the performance of RFID labels and tags.

- Adjustable test recipe and acceptance criteria
- Multiple tests in a single recipe
- Wide frequency band in use
- RF quality testing
- Reading and verifying memory content
- Quality variance data
- Proof of quality in log files



### ITEC

Jonkerbosplein 52  
6534 AB Nijmegen  
The Netherlands  
info@ITECequipment.com

### Voyantic Ltd.

Takomotie 1-3 • 00380 Helsinki • FINLAND  
P: +358-20-788-8190  
sales@voyantic.com  
<https://voyantic.com>